

## IN THE CLAIMS

1. (Original) A method of manufacturing a printed circuit board that can be connected with a pin connector, the method comprising:
  - applying a first solder screen printing to a tap unit on a first side of the printed circuit board;
  - solidifying the first solder screen printing;
  - applying a second solder screen printing to the tap unit on a second side of the printed circuit board; and
  - solidifying the second solder screen printing.
2. (Original) The method of claim 1, wherein the method further comprises:
  - covering the tap unit with flux;
  - inserting the pin connector into the tap unit; and
  - connecting the pin connector to the tap unit by performing high temperature reflow.
3. (Original) The method of claim 1, wherein the method further comprises:
  - covering a junction area of the pin connector with flux, wherein the junction area is connected to the tap unit where the solder has solidified;
  - inserting the pin connector into the tap unit where the solder has solidified; and
  - connecting the pin connector to the tap unit by performing high temperature reflow.
4. (Original) The method of claim 1, wherein applying the first solder screen printing to the tap unit on the first side of the printed circuit board is performed when the first solder screen printing is applied to pads on the first side of the printed circuit board on which electrical components are to be mounted.
5. (Original) The method of claim 1, wherein applying a second solder screen printing to the tap unit on a second side of the printed circuit board is performed when solder screen printing is applied to pads on the second side of the printed circuit board on which electrical components are to be mounted.

6. (Original) The method of claim 1, wherein solidifying the first solder screen printing comprises performing high temperature reflow.

7. (Currently amended) The method of claim 6, wherein solidifying the first solder screen printing is performed when high temperature reflow is performed after mounting the electrical components to be mounted on the first side of the printed circuit board.

8. (Original) The method of claim 1, wherein solidifying the second solder screen printing comprises performing high temperature reflow.

9. (Currently amended) The method of claim 8, wherein solidifying the second solder screen printing is performed when high temperature reflow is performed after mounting the electrical components to be mounted on the second side of the printed circuit board.

10. (Withdrawn) A computer readable medium having embodied thereon a computer program for a method of manufacturing a printed circuit board that can be connected with a pin connector.

11. (Withdrawn) A printed circuit board made by using the method of claim 1, the printed circuit board comprising:

a printed circuit unit on which pads are formed to mount chips electrically connected to one another or electrical components thereon, the pads being electrically connected one another; and

a tap unit that is electrically connected with the printed circuit unit, has solidified solder formed thereon, and can be connected with an external pin connector.